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cont'd

moving the light output along a path of the frit layer at a predetermined rate to carbonize the frit layer to effect release of the windscreen panel from the frame.

47. (NEW) A method of releasing a windscreen panel from a frame to which the windscreen panel is bonded by interposed bonding material, the method comprising the steps of:

directing light output from an array of laser diodes at a frit layer on an inside face of the windscreen panel about a periphery thereof and conforming to the frame;

providing the light output at a wavelength absorbed by the frit layer; and

moving the light output along a path of the frit layer at a predetermined rate to carbonize the frit layer to effect release of the windscreen panel from the frame.

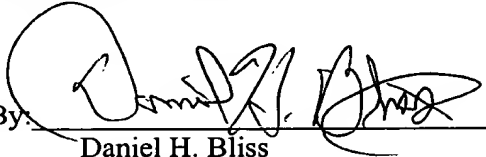
REMARKS

New claims 46 and 47 have been added. Claims 1 through 47 remain in the application.

Attached to this Preliminary Amendment is a new Declaration and Power of Attorney claiming the benefit of 35 U.S.C. § 120 of prior U.S. patent application Serial No. 09/133,854 and 08/693,060. Applicants have amended the Specification to contain a specific reference to Serial No. 09/133,854, which is still pending and Serial No. 08/693,060.

Applicants have added new claims 46 and 47 to claim additional subject matter to which Applicants are entitled. Applicants look forward to early consideration of the pending claims.

Respectfully submitted,

By: 
Daniel H. Bliss
Reg. No. 32,398

BLISS McGLYNN, P.C.
2075 West Big Beaver Road, Suite 600
Troy, Michigan 48084
(248) 649-6090

Date: April 20, 2000

Docket: 2170.00013